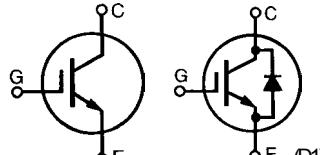


HiPerFAST™ IGBT

IXGH39N60B
IXGH39N60BD1
IXGT39N60B
IXGT39N60BD1

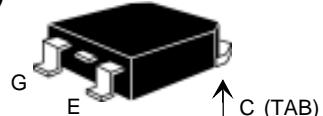
V_{CES} = 600 V
 I_{C25} = 76 A
 $V_{CE(sat)}$ = 1.7 V
 t_{fi} = 200 ns



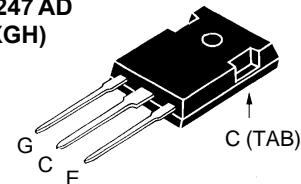
Preliminary data

Symbol	Test Conditions	Maximum Ratings		
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	600	V	
V_{CGT}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	600	V	
V_{GES}	Continuous	±20	V	
V_{GEM}	Transient	±30	V	
I_{C25}	$T_C = 25^\circ\text{C}$	76	A	
I_{C90}	$T_C = 90^\circ\text{C}$	39	A	
I_{CM}	$T_C = 25^\circ\text{C}$, 1 ms	152	A	
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 22 \Omega$ Clamped inductive load	$I_{CM} = 76 \text{ A}$ @ 0.8 V_{CES}		
P_c	$T_C = 25^\circ\text{C}$	200	W	
T_J		-55 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-55 ... +150	°C	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C	
M_d	Mounting torque (M3)	TO-247	1.13/10Nm/lb.in.	
Weight		TO-247 AD TO-268	6 4	g

TO-268
(IXGT)



TO-247 AD
(IXGH)



G = Gate,
C = Collector,
E = Emitter,
TAB = Collector

Features

- International standard packages JEDEC TO-247 AD & TO-268
- High current handling capability
- Newest generation HDMOS™ process
- MOS Gate turn-on - drive simplicity

Applications

- PFC circuits
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies

Advantages

- High power density
- Very fast switching speeds for high frequency applications

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	Min.	Typ.	Max.
BV_{CES}	$I_c = 250 \mu\text{A}$, $V_{GE} = 0 \text{ V}$	39N60B	600		V
	$I_c = 750 \mu\text{A}$	39N60BD1	600		
$V_{GE(th)}$	$I_c = 250 \mu\text{A}$, $V_{CE} = V_{GE}$	39N60B	2.5	5.0	V
	$I_c = 500 \mu\text{A}$	39N60BD1	2.5	5.0	V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$	$T_J = 25^\circ\text{C}$	39N60B	200	μA
	$V_{GE} = 0 \text{ V}$	$T_J = 125^\circ\text{C}$	39N60B	1	mA
		$T_J = 125^\circ\text{C}$	39N60BD1	3	mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			±100	nA
$V_{CE(sat)}$	$I_c = I_{90}$, $V_{GE} = 15 \text{ V}$			1.7	V

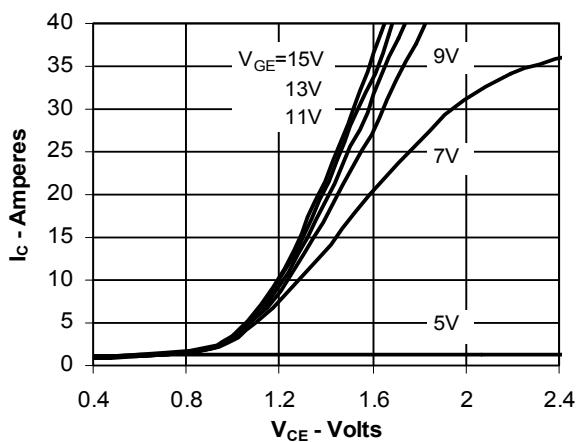
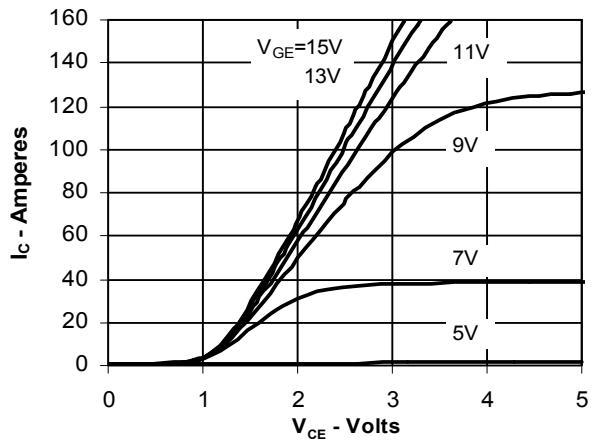
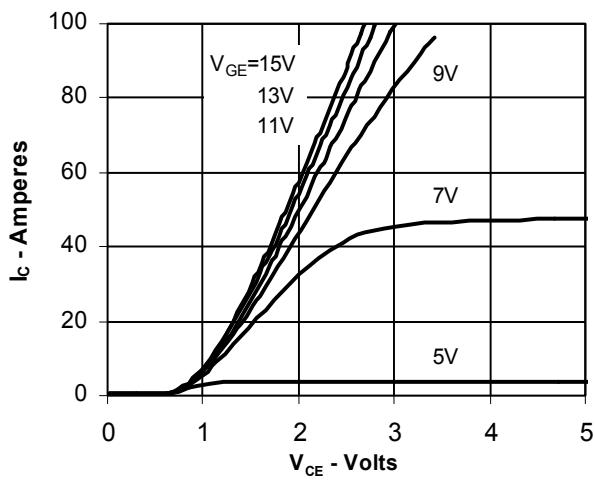
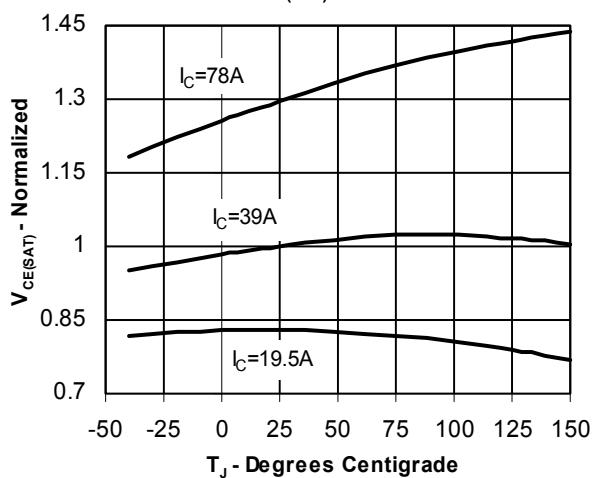
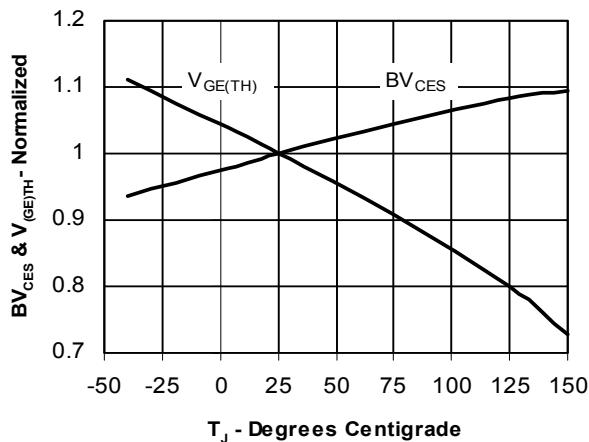
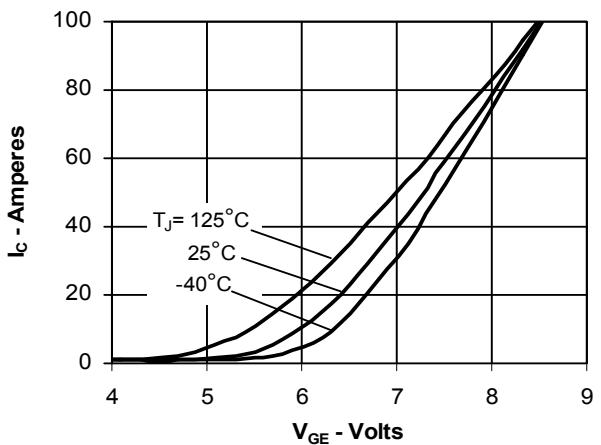
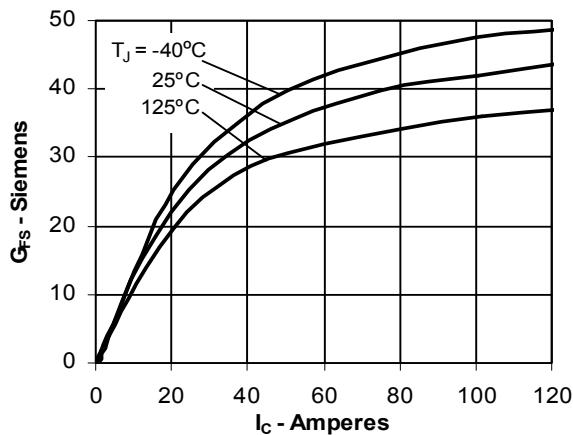
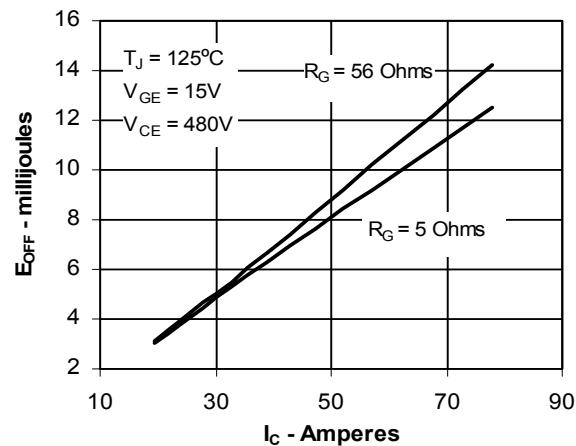
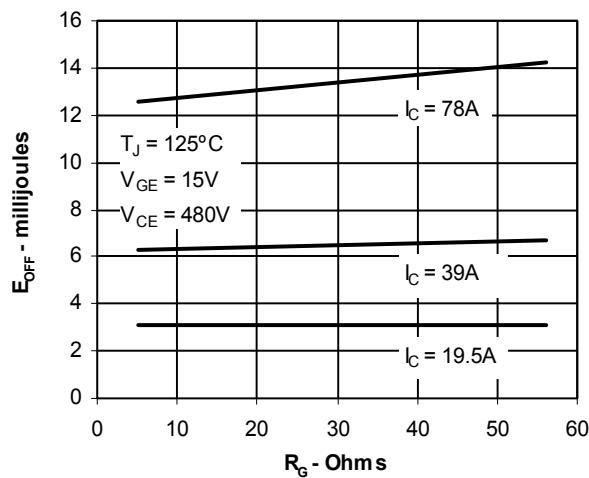
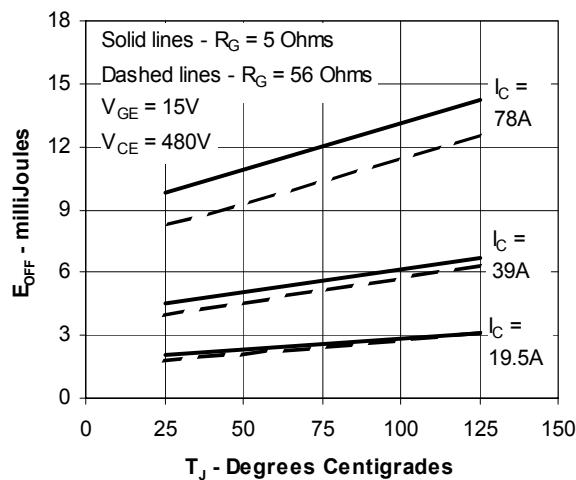
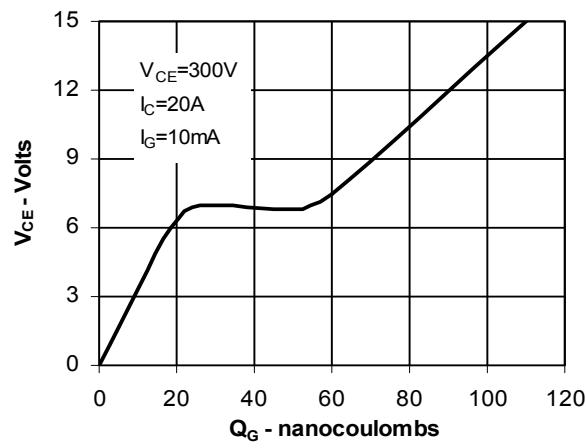
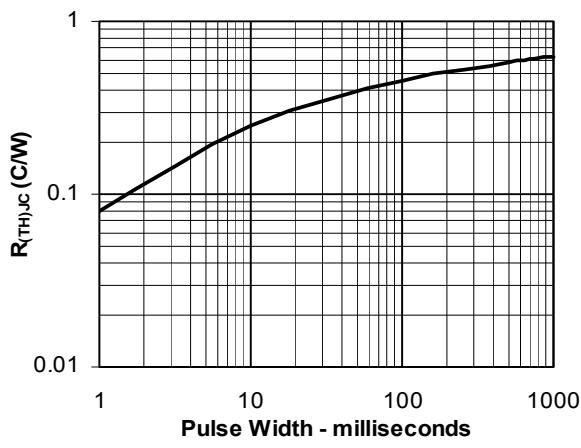
Fig. 1. Saturation Voltage Characteristics @ 25 Deg. C**Fig. 2. Extended Output Characteristics @ 25 Deg. C****Fig. 3. Saturation Voltage Characteristics @ 125 Deg. C****Fig. 4. Temperature Dependence of $V_{CE(SAT)}$** **Fig. 5. BV_{CES} & $V_{(GE)TH}$ vs. Junction Temperature****Fig. 6. Admittance**

Fig. 7. Transconductance

Fig. 8. Dependence of E_{OFF} on I_c

Fig. 9. Dependence of E_{OFF} on R_G

Fig. 10. Dependence of E_{OFF} on Temperature

Fig. 11. Gate Charge

Fig. 12. Transient Thermal Response


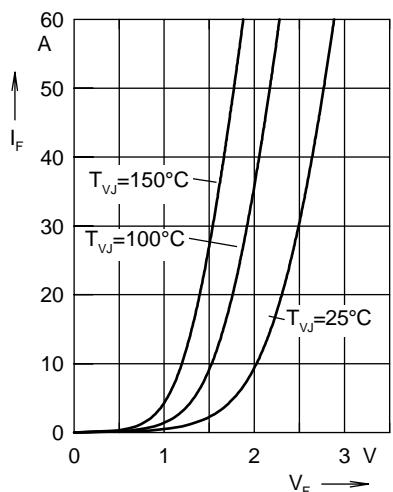


Fig. 12 Forward current I_F versus V_F

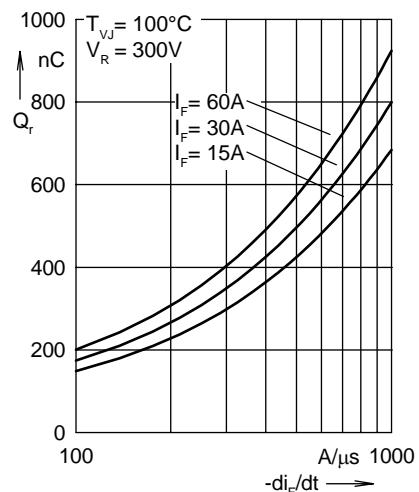


Fig. 13 Reverse recovery charge Q_r versus $-di_F/dt$

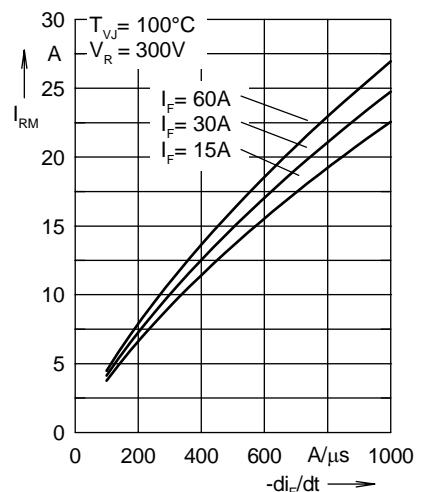


Fig. 14 Peak reverse current I_{RM} versus $-di_F/dt$

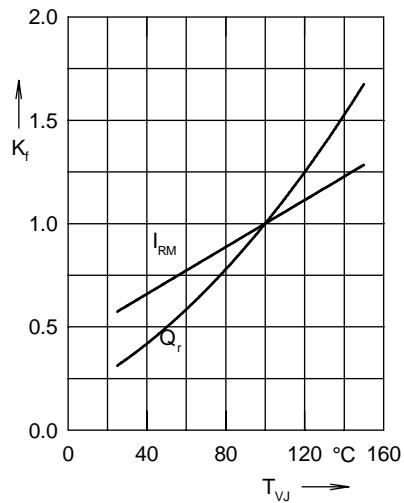


Fig. 15 Dynamic parameters Q_r , I_{RM} versus T_{VJ}

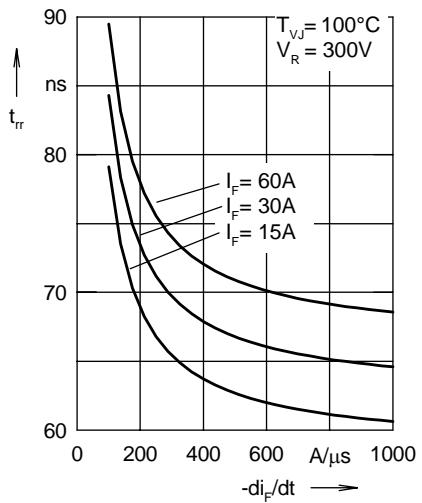


Fig. 16 Recovery time t_{rr} versus $-di_F/dt$

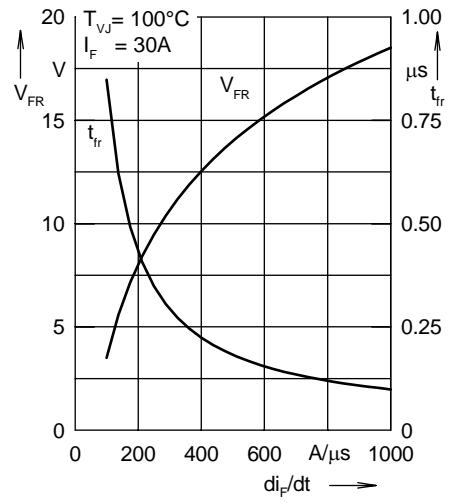


Fig. 17 Peak forward voltage V_{FR} and t_{fr} versus di_F/dt

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162

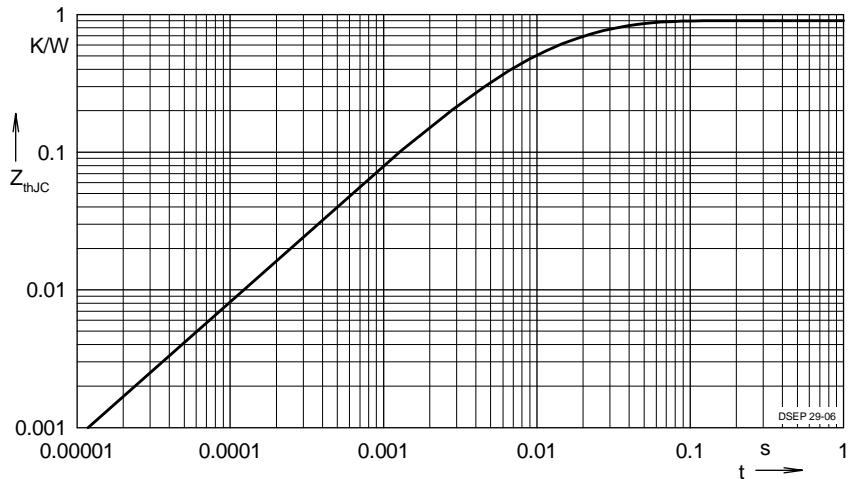


Fig. 18 Transient thermal resistance junction to case